

IMT-TE1009

NON-CONDUCTIVE DIE ATTACH ADHESIVE

IMT-TE1009 is a single component, electrically insulating but thermally conductive die attach adhesive. This product is designed to meet demanding semiconductor and microelectronics die attach applications. IMT-TE1009 is snap curable as well as fast cure in box oven. It possesses excellent adhesion strength to various leadframes, substrates and flex-tape.

IMT-TE1009 does not contain solvent and is a 100% solid system. It complies to RoHS3, EU directive 2015/863 as well as Substances of Very High Concern (SVHC) published by ECHA.

This die attach adhesive is packed in syringe for use in automated, high speed dispensing equipment.

TYPICAL PROPERTIES*

Cure Conditions
(Actual holding temperature & time
excludes ramp up & down)

1. Snap cure at 180°C for 30sec
2. Snap cure at 160°C for 90sec
3. Oven cure at 150°C for 15min

Pot Life
Shelf Life

24 hours at room temperature
12 months at -40°C

Physical Properties

Color
Consistency
Specific Gravity
Viscosity @5rpm, 25°C
Thixotropic Index @0.5/5rpm
Glass Transition Temperature
Shore D Hardness
Die Shear Strength

Light beige before cure & brown after cure
Smooth, thixotropic paste
1.25
15,500cPs
4.05
> 90°C
> 85
> 15Kgf per 3.2x2mm chip on Ag plated leadframe

Electrical & Thermal Properties

Volume Resistivity
Dielectric Constant (10KHz)
Dissipation Factor
Thermal conductivity

> 1 x 10¹³Ωcm
3.9
0.009
0.5W/mK

Ionic Contents

Chloride, Cl-
Sodium, Na+
Potassium, K+

< 20ppm
< 5ppm
< 5ppm

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* The information is based on data and tests believed to be accurate. In-Mat Technologies (S) Pte Ltd makes no warranties as to its accuracy and assumes no liability in connection with the use or inability to use this product.